

CALL FOR PAPERS

ABOUT EPTC

The 21st Electronics Packaging Technology Conference (EPTC 2019) is an international event organized by the IEEE RS/EPS/EDS Singapore Chapter and co-sponsored by IEEE Electronics Packaging Society (EPS). EPTC 2019 will feature keynotes, technical sessions, short courses, forums, an exhibition, social and networking activities, including a banquet for all attendees. It aims to provide a good coverage of technology developments in all areas of electronics packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet with leading international experts.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in the Asia Pacific and is well attended by experts in all aspects of packaging technology from all over the world. EPTC is the flagship conference of IEEE EPS in Region 10.

CONFERENCE TOPICS

You are invited to submit abstract(s), presenting new developments in the following categories:

- ❑ **Advanced Packaging:** Advanced Flip-chip, 2.5D & 3D, PoP, embedded passives & actives on substrates, System in Packaging, Embedded chip packaging technologies, Panel level packaging, RF, Microwave & Millimeter-wave, Power and Rugged Electronics Packaging, etc.
- ❑ **TSV/Wafer Level Packaging:** Wafer level packaging (Fan in/Fan out), Embedded chip packaging, 2.5D/3D integration, TSV, Silicon & Glass interposer, RDL, Bumping technologies, etc.
- ❑ **Interconnection Technologies:** Au/Ag/Cu/Al Wire-bond / Wedge bond technology, Flip-chip & Cu pillar, Solder alternatives (ICP, ACP, ACF, NCP, ICA), Cu to Cu, Wafer level bonding & die attachment (Pb-free), etc.
- ❑ **Emerging Technologies:** Packaging technologies for MEMS, biomedical, Optoelectronics, Internet of things, Photovoltaic, Printed electronics, Wearable electronics, Photonics, LED, etc.
- ❑ **Materials and Processing:** Advanced materials (such as photoresist, polymer dielectrics, solder, die attach, underfill), Substrates, Lead-frames, PCB for advanced packaging, Assembly processes using advanced materials, etc.
- ❑ **Assembly and Manufacturing Technology:** Assembly equipment automation and improvements, Embedded/Hybrid Package Manufacturing Processes, Warpage Control and Management in Board Level Assembly, Thin Die/Package Handling and Assembly, Large/Ultra Large Package (SiP, SIM, MCP) Integration and Processing, Panel Level Manufacturing, Smart Manufacturing technology, Data analytics, Advanced metrology, Machine learning.
- ❑ **Electrical Simulation & Characterization:** Power plane modeling, Signal integrity analysis by simulations and characterization, 2D/2.5D/3D package level high-speed signal design, Characterization and test methodologies.

- ❑ **Mechanical Simulation & Characterization:** Thermo-mechanical, Moisture, Fracture, Fatigue, Vibration, Shock and drop impact modeling and characterization. Process modeling. Chip-package interaction, etc.
- ❑ **Thermal Characterization & Cooling Solutions:** Thermal modeling and simulation, Component, system and product level thermal management and characterization
- ❑ **Quality, Reliability & Failure Analysis:** Component, board, system and product level reliability assessment, Interfacial adhesion, Accelerated testing, Failure characterization, etc.

IMPORTANT DATES

Online abstract submission start	25 th Apr 2019
Closing of abstract submission (Extended)	15 th Jul 2019
Notification of acceptance	30 th Aug 2019
Submission of manuscript	30 th September 2019

ABSTRACT AND PAPER SUBMISSION

Abstracts are solicited which describe original and unpublished work. The abstract should be at least 500-750 words long and clearly state the purpose, methodology, results (including data, drawings, graphs and photographs) and conclusions of the work. Authors can indicate preference of oral or poster presentation.

All submissions must be in English and should be made via the online submission system found at <http://www.eptc-ieee.net>. The required file format is Adobe Acrobat® PDF or MS Word in one single file for each submission.

The abstracts must be received by 15th July 2019. Authors must include their affiliation, mailing address, telephone number and email address. Authors will be notified of paper acceptance and publication instructions by 30th Aug 2019. The final manuscript for publication in the conference proceedings is due by 30th September 2019. The conference proceedings are an official IEEE publication and accepted papers that are registered and presented (oral & poster) will be available in IEEE Xplore.

BEST PAPER AWARDS

Awards will be given to the best oral papers from Academia, Industry, Students, and to the best interactive papers. More details can be found at <http://www.eptc-ieee.net>

CALL FOR SHORT COURSES

The conference program includes short courses which will be conducted by leading experts in the field. Details will be updated in the conference website. Attendees are entitled to one PDC course. Proposals for short courses can be submitted to pdcc@eptc-ieee.net

CALL FOR EXHIBITION / SPONSORSHIP PARTICIPATION

A tabletop exhibition featuring suppliers of materials, equipment and services to the microelectronics packaging and manufacturing, will be held during the conference. For details, please email to exhibition@eptc-ieee.net and sponsorship@eptc-ieee.net.

EPTC 2019: website: <http://www.eptc-ieee.net> Email: secretariat@eptc-ieee.net Join us on: [Linkedin](#) [EPTC OC]